

SMALL SIGNAL SCHOTTKY DIODE

DESCRIPTION

Metal to silicon junction diode primarily intended for UHF mixers and ultrafast switching applications.



MINIMELF
(Glass)

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage		15	V
I_F	Forward Continuous Current	$T_I = 25^\circ\text{C}$	30	mA
I_{FSM}	Surge non Repetitive Forward Current	$t_p \leq 1\text{s}$	60	mA
T_{stg} T_j	Storage and Junction Temperature Range		- 65 to +150 - 65 to +125	$^\circ\text{C}$ $^\circ\text{C}$
T_L	Maximum Temperature for Soldering during 15s		260	$^\circ\text{C}$

THERMAL RESISTANCE

Symbol	Test Conditions	Value	Unit
$R_{th(j-l)}$	Junction-leads	400	$^\circ\text{C/W}$

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ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
V_{BR}	$T_{amb} = 25^\circ C$	$I_R = 10\mu A$	15			V
V_F (1)	$T_{amb} = 25^\circ C$	$I_F = 1mA$			0.38	V
	$T_{amb} = 25^\circ C$	$I_F = 10mA$			0.5	
	$T_{amb} = 25^\circ C$	$I_F = 30mA$			1	
I_R (1)	$T_{amb} = 25^\circ C$	$V_R = 6V$			0.1	μA

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
C	$T_{amb} = 25^\circ C$	$V_R = 1V$	$f = 1MHz$			1.1	pF
τ	$T_{amb} = 25^\circ C$	$I_F = 20mA$	Krakauer Method			100	ps
F (2)	$T_{amb} = 25^\circ C$	$f = 1GHz$			6	7	dB

(1) Pulse test: $t_p \leq 300\mu s$ $\delta < 2\%$.

(2) Noise figure test :

- diode is inserted in a tuned stripline circuit
- local oscillator frequency 1GHz
- local oscillator power 1mW
- intermediate frequency amplifier, tuned on 30MHz, has a noise figure 1.5dB

Matched batches available on request. Test conditions (forward voltage and/or capacitance) according to customer specification.

Figure 1. Forward current versus forward voltage (typical values).

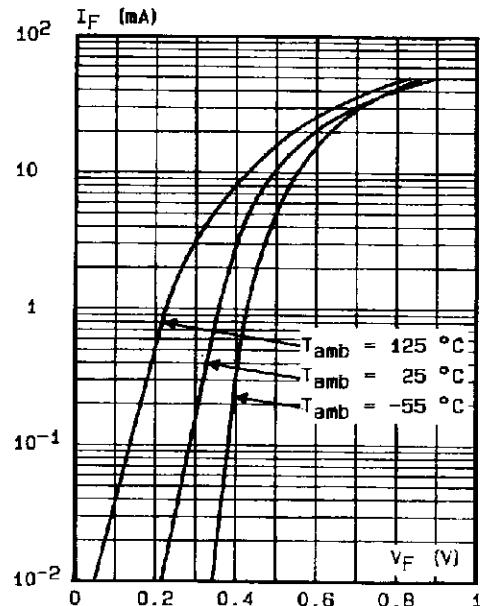


Figure 2. Capacitance C versus reverse applied voltage V_R (typical values).

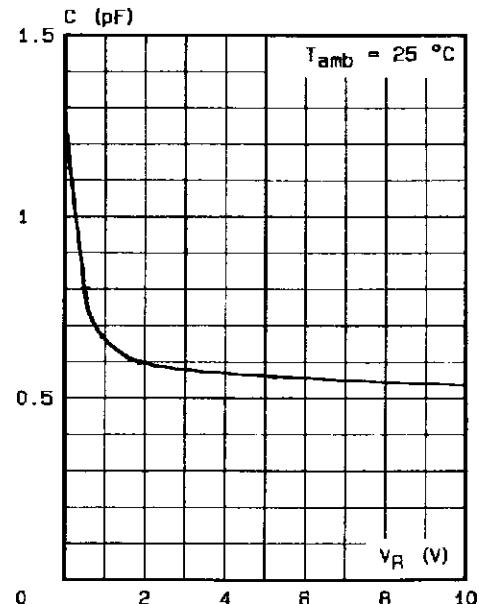


Figure 3. Reverse current versus ambient temperature.

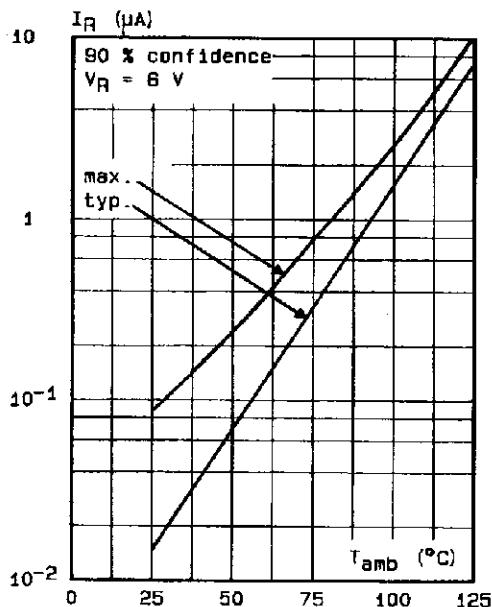
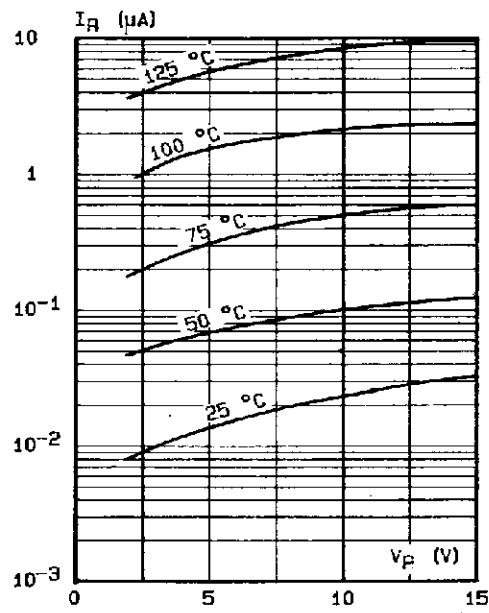


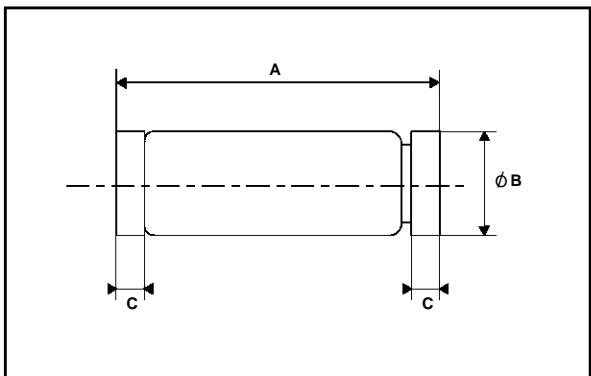
Figure 4. Reverse current versus continuous reverse voltage (typical values).



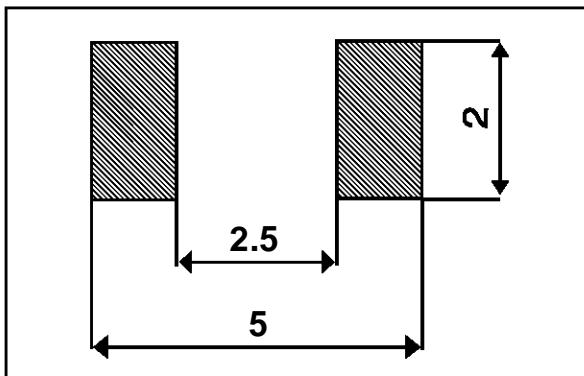
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PACKAGE MECHANICAL DATA

MINIMELF Glass



FOOT PRINT DIMENSIONS (Millimeter)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.3	3.6	0.130	0.142
B	1.59	1.62	0.063	0.064
C	0.4	0.5	0.016	0.020

Marking: ring at cathode end.

Weight: 0.05g

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